

METHOD AND APPARATUS FOR CONTROLLED BROADBAND MICROWAVE HEATING

BACKGROUND OF THE INVENTION

[0001] Field of the Invention

[0002] The invention pertains to the field of processing materials using microwave energy. More particularly the invention pertains to apparatus and methods for generating precise levels of microwave power across a broad frequency range.

[0003] Description of Related Art

[0004] The use of microwave power for industrial processes, including heating, is well established and practiced on a large scale, particularly for applications such as drying, where the principle material to be acted upon is water. It has also more recently been applied to the curing of thermoset polymers and adhesives. It is well known that the use of a single-frequency microwave source in a multimode cavity can lead to non-uniformities related to the establishment of standing waves within the cavity. To solve this problem, Variable Frequency Microwave (VFM) systems were developed, as taught, for example, in U.S. Pat. Nos. 5,521,360; 5,721,286; and 5,961,871.

[0005] In general, VFM systems have a multimode applicator cavity and a microwave power supply capable of broadband operation; here, broadband is defined as the capability to sweep the applied frequency over some useful range about a chosen center frequency. Model calculations taught in U.S. Pat. No. 5,961,871 show the relationship between bandwidth, cavity size, and center frequency on the overall spatial uniformity of microwave energy in the cavity **18**. The block diagram, FIG. 1, shows the prior art for a control system that includes a microwave power supply that typically has a microwave frequency source, comprising a voltage-tunable YIG oscillator and a voltage-controlled attenuator, whereby signals from a control system are applied to produce a

small-signal microwave output of a given frequency, bandwidth, waveform, or other selected characteristics. This microwave signal is then passed to a high power microwave amplifier, typically a TWT, to produce a high power signal having the aforementioned selected characteristics. A control system monitors the forward and reverse microwave output power. A second control loop monitors the process using temperature, as shown, or another suitable process parameter and provides closed loop feedback to adjust the level of microwave power automatically.

[0006] As shown in Figure 1:

Small signal components 10 include: a YIG oscillator **11**, which generates microwave frequencies at low power; and a voltage controlled attenuator **12**, which adjusts small signal RF power level. A fixed attenuator (not shown) limits maximum signal strength to a safe level, and an RF Bandpass Filter **13** ensures RF signal is in band for high power amplifier.

High Power Components include: a High Power Amplifier **14**, which generates high power output from small signal input; and an Isolator **15**, which prevents reflected power from the curing cavity reaching the high power amplifier.

Measurement Components include: a Directional coupler **16**, which provides a highly attenuated RF signal useful for RF power measurement. Crystal Detectors **19** convert the low level RF signal from the Directional Coupler to a useful DC control voltage **20a**, **20b**.

[0007] In addition the prior art control system contains software based self calibration procedures to account for multiple systemic nonlinearities, e.g., the variation of TWT gain across the working bandwidth, FIG. 2. The microwave uniformity obtained with the aforementioned calibration routine, combined with closed-loop process control produce a level of microwave power output that has proven suitable for applications such as curing adhesives, curing polymers, processing ceramics in various applications, particularly those in electronics manufacturing.

[0008] However, in the development of processes for high value products such as thermal processing of semiconductor wafers, including coatings on wafers, it was found that the prior art variable or swept frequency control systems were unable to produce the precise level of control needed, and furthermore, that the calibration and setup procedures were cumbersome and time-consuming.

[0009] Objects and Advantages

[0010] Objects of the invention include: providing an improved broadband microwave source for heating and other purposes; providing a method for controlled microwave heating; providing a method for broadband microwave processing capable of open-loop operation; providing an improved method for processing semiconductor wafers; providing a VFM control system that is more robust and stable under varying environmental conditions; and providing a VFM control system that is easier to set up and calibrate.

[0011] These and other objects and advantages of the invention will become apparent from consideration of the following specification, read in conjunction with the drawings.

SUMMARY OF THE INVENTION

[0012] According to one aspect of the invention, a broadband microwave heating apparatus comprises:

- an applicator cavity for exposing a workpiece to microwave energy;
- a microwave power supply connected to the cavity, the power supply comprising:
 - a small signal RF source comprising at least a voltage controlled microwave oscillator and a voltage controlled attenuator that are both thermally stabilized at a selected temperature above ambient;
 - a high power microwave amplifier to amplify the small signal to a usable power level for heating;

forward and reflected power detectors, the detectors thermally stabilized and separated from one another by a microwave isolator; and,

a control system using a power regulator to adjust output power using detected forward power compared to demanded forward power.

[0013] According to another aspect of the invention, a broadband microwave power supply comprises:

a small signal RF source comprising at least a voltage controlled microwave oscillator and a voltage controlled attenuator that are both thermally stabilized at a selected temperature above ambient;

a high power microwave amplifier to amplify the small signal to a usable power level for heating;

forward and reflected power detectors, the detectors thermally stabilized and separated from one another by a microwave isolator; and,

a control system including a power regulator to adjust output power using detected forward power compared to demanded forward power.

[0014] According to another aspect of the invention, an integrated, low power microwave source comprises:

a voltage controlled oscillator (VCO);

a voltage controlled attenuator (VCA);

a heater and temperature control circuit; and,

a package containing the VCO, VCA, heater, and temperature control circuit and having external connections for DC power, DC frequency control voltage, DC amplitude control voltage, and RF signal out.

[0015] According to another aspect of the invention, a method of heating materials using broadband microwave power, comprises the steps of:

placing a selected workpiece in a multi-mode microwave applicator cavity;

providing a microwave power supply in communication with the cavity, the power supply including a small-signal RF generating circuit, a high power microwave amplifier,

and forward and reflected power detectors, the detectors thermally stabilized and separated from one another by an isolator;

heating at least some of the components of the small-signal RF circuit to a selected temperature above ambient; and,

providing a control system to perform the following functions:

run an automatic power leveling routine to automatically generate an autolevel table and download said autolevel table to the control system;

provide an automatic power control system to limit the rate of power adjustment.

BRIEF DESCRIPTION OF THE DRAWINGS

[0016] The drawings accompanying and forming part of this specification are included to depict certain aspects of the invention. A clearer conception of the invention, and of the components and operation of systems provided with the invention, will become more readily apparent by referring to the exemplary, and therefore non-limiting embodiments illustrated in the drawing figures, wherein like numerals (if they occur in more than one view) designate the same elements. The features in the drawings are not necessarily drawn to scale.

[0017] Figure 1 illustrates the system architecture of the Prior Art microwave heating system.

[0018] Figure 2 illustrates schematically the gain versus frequency for several high power amplifiers based on vendor data.

[0019] Figure 3 illustrates the change in YIG oscillator output with time as the surface temperature of the device changes.

[0020] Figure 4 illustrates the change in crystal detector output versus temperature for several devices.

[0021] Figure 5 illustrates the system architecture of the microwave heating system in accordance with one aspect of the invention.

[0022] Figure 6 illustrates the stability and reproducibility of power output in the inventive system.

[0023] Figure 7 illustrates a thermally stabilized small-signal RF circuit in accordance with one aspect of the invention.

[0024] Figure 8 illustrates an integrated, thermally stabilized small-signal RF circuit in accordance with one aspect of the invention.

[0025] Figure 9 compares forward power measurements 9B, 9D into a dummy load 9A and into a short 9C, respectively, using the configuration of the Prior Art.

[0026] Figure 10 compares forward power measurements 10B, 10D into a dummy load 10A, and into a short 10C, respectively, using the configuration of the present invention.

[0027] Figure 11 shows the crystal detector output 11A, with and without attenuation and amplification using the configuration shown in 11B.

[0028] Figure 12 shows the autolevel process of the Prior Art.

[0029] Figure 13 shows the autolevel process in accordance with one aspect of the current invention.

[0030] Figure 14 compares the power output across the frequency band using the present invention, 14B and using the Prior Art, 14A.

[0031] Figure 15 illustrates the typical gain drift of a high power amplifier of the type used in broadband microwave heating systems.

[0032] Figure 16 illustrates the architecture for automatic forward power regulation in accordance with one aspect of the invention.

DETAILED DESCRIPTION OF THE INVENTION

[0033] The invention provides an novel and improved microwave processing technique for the treatment of high value or critical materials such as semiconductor wafers, which require uniformity and a high degree of process stability.

[0034] The rapid processing approach involves the use of Variable Frequency Microwave (VFM) heating, a well-known process taught in at least the following U. S. Patents, each of which is incorporated herein by reference in its entirety: 5,321,222; 5,721,286; 5,961,871; 5,521,360; and 5,738,915. For example, U.S. Patent No. 5,738,915 by Fathi et al. teaches the use of VFM for rapid curing of polymeric films on semiconductor wafers. It should be noted that although single or fixed frequencies can be used for microwave heating of semiconductors, they generally produce non-uniform heating, and when metal films are involved arcing with these films becomes a serious issue. However, the continuous sweeping of frequencies over the bandwidth being used with VFM, as taught in the aforementioned references, reduces the potential for arcing and subsequent damage. Numerous kinds of wafers with integrated circuits have been exposed to VFM and it has been demonstrated that there is no damage to the circuits or their functionality. The use of VFM provides more rapid processing as compared to other annealing furnaces. Additional process monitoring techniques are taught by Fathi et al. in U.S. Patent 5,648,038, the entire disclosure of which is incorporated herein by reference.

[0035] In developing VFM systems for semiconductor processing, comprehensive investigation showed that existing control strategies were unable to maintain the

required level of precision, for several reasons. Applicants found significant gain sensitivity (output variation) of the small signal components, specifically the YIG Oscillator **11** and Voltage controlled attenuator **12** as a function of the environmental operating temperature. In addition the stability of the YIG oscillator output from self heating after power on had a measureable impact. FIG. 3 shows the change in power output of a typical YIG oscillator as a function of time, showing power decreasing from self-heating of the device, and then a significant change when a secondary heat source is applied to the baseplate. Applicant also found that the gain of high power components such as the TWTA will drift, or vary unpredictably with time and temperature as shown in FIG. 15. Furthermore the extremely high gain, physical size and power consumption of these components make it prohibitive to stabilize them using traditional techniques. In addition to the larger components, the gain drift of the other high power components including the isolator and the numerous small signal transmission line components are difficult to quantify.

[0036] Applicants found significant degradation in amplitude output of the measurement components relative to the local operating environment temperature. FIG. 4 shows the effect on the crystal detectors **19** used to measure RF output on the directional coupler as the local operating environment temperature increased). Applicants further found that crystal detector output saturates (gain rolls off) as the measured power level increases as shown in FIG. 11. This in turn provides poorer signal resolution and a loss of control accuracy. In addition, crystal detectors provide a low level DC signal, typically less than 1 VDC referenced from local ground. Variations in ground potential between the crystal detector location and the control system location introduce significant error into the measurement and thus the accuracy of the power control.

[0037] Applicants found that the forward power port of high power measurement devices, such as the directional couplers **16** typically used to measure waveguide power were highly sensitive to reflected power. Reflected power cannot be eliminated when launching into a closed chamber **18**. Furthermore, reflected power is a function of

launch frequency and process chamber loading. This means that the forward power signal lacks fidelity across the launch spectrum.

[0038] Applicants determined that the prior art calibration techniques used to generate uniform microwave output power as a function of frequency were not sufficiently precise or consistent run-to-run. Further improvements in calibration accuracy using the prior art were determined to take exponentially longer times to complete.

[0039] As will be shown in the examples that follow, Applicants have discovered that a novel combination of hardware and software features not only greatly improves process uniformity, but has provided unexpected synergies that allow the system to operate in a desirable open-loop process control mode in addition to a traditional closed-loop process control mode.

[0040] Applicants have discovered and demonstrated innovations that are in three major categories:

[0041] First: Amplitude Stability including: 1. small signal gain stabilization with temperature, and 2. overall large signal stability with respect to drift with a unique automatic power regulation algorithm.

[0042] Second: Measurement Integrity including: 3. directional coupler isolation from reflected power, 4. crystal detector stabilization with temperature, 5. Fixed attenuation offset of the crystal detector output to improve the sensitivity range of the crystal detector, 6. ground isolation to remove DC offsets in the microwave power measurement control system and 7. amplification to further increase crystal detector sensitivity for accurate measurements.

[0043] Third: Frequency Uniformity including: 8. an advanced autolevel routine that provides precise power resolution, self identifies the high power saturation drive levels, and provides a useful diagnostic history file. One unexpected benefit has been

discovery of an algorithm that provides both faster and much more accurate self calibration (Autolevel) operations.

[0044] Applicants have discovered that attributes of all three categories are interconnected and must be present exist in order to obtain high quality control of a broadband microwave power source. It has become clear that precision control of power cannot be done without stable sources and high fidelity measurement. Furthermore, precision control of amplitude vs. frequency for a swept frequency broadband system cannot be done without these same controls. The improved apparatus is shown in FIG. 5 and will be further explained in the following examples.

[0045] The surprising and unexpected results of the advanced controls include: 1. improved accuracy, and 2. high run to run repeatability as shown in FIG 6. These capabilities are required for open loop process control. Furthermore, these capabilities extend broadband microwave suitability to applications where feedback signals are not reliable because of accessibility, noise, or other limits on process measurement.

EXAMPLE

[0046] Small-signal Chain: The various components of the small-signal RF circuit **10** are shown in FIG. 1. The selected microwave frequency is generated by a voltage controlled YIG oscillator (VCO) **11** (e.g. Teledyne 1062 MNAS1062C-DA); it will be understood that any suitable VCO may be used, including solid state devices (e.g. RFMD model RFVC1802).

[0047] Initial power level control is done with a voltage controlled attenuator (VCA) **12** (e.g. Pulsar Microwave model AAT-24-479/5SL or Anaren PIN diode attenuator model 61527). Optional components may include a fixed attenuator (e.g.: Inmet Corporation part number 12A-30) and a RF Bandpass Filter **13** (e.g. Lark Filter part number 4B6250-H800-6AA). Each of the aforementioned components will have some

characteristic temperature coefficient as shown for the case of the YIG oscillator in FIG. 3. This may be dealt with by either of two approaches: 1. The thermal behavior of each component may be mapped and incorporated as a variable into the control system; or, 2. A particular component may be intentionally heated to a temperature that is above any expected ambient temperature but below the upper operating limit of that component (typically 30 to 50°C). Option 2 is sometimes referred to as “ovenizing” and is occasionally employed in precision measurement equipment, for example to eliminate frequency drift in a crystal oscillator (see, e.g., U.S. Pat. 5,770,977, issued June 23, 1998 to Uurtamo) but to Applicants’ knowledge the approach has never been tried in microwave power systems to account for amplitude stability, or other types of temperature-dependent physical or electrical phenomena.

[0048] As shown in FIG. 7, Applicants have discovered that by mounting the entire small-signal RF chain on a common platform **70**, the entire chain can be “ovenized” to a single temperature by a backside heater **75**, controlled using temperature sensor **72** and safety thermostat **73**, leading to remarkable amplitude output stability of the small-signal RF circuit. The result is a stabilized small signal RF circuit **10’**.

[0049] It will be understood that it is within the scope of the invention to ovenize the components individually, as may be needed if one of the control components such as the VCA is located in a TWTA. However, the synergy of eliminating independent thermally-related variations in the individual components surprisingly simplifies the overall system control process. It is particularly convenient and efficient to ovenize the entire small signal chain because these components are most often closely coupled.

EXAMPLE

[0050] Small-signal Chain: The various components of the improved small-signal RF circuit **10'** may be further consolidated into a hybrid module (**10''**). An example is shown in FIG 8 where the VCO (**11'**), optional Fixed Attenuator **71'**, VCA **12'**, and optional RF Bandpass Filter **13'** are integrated as components onto a PCB or hybrid module. This module may further incorporate a self contained, self controlled heater and control circuit module **80**. Such an integrated, stabilized RF circuit is suitable for incorporating into all manner of devices including test equipment, communications equipment, and the like, using any conventional interconnect methods.

[0051] Power Measurement: Improved power control is only as good as the accuracy of the power measurement. The established art for power measurement in a microwave system is to use a coupler to create a low level RF signal and a crystal detector to convert the RF signal to a DC control voltage.

[0052] Couplers such as Apollo Microwaves p/n 16160-3, or Lieder Development p/n L137CG-50SF-CF-5.85-7.0, include a strategically located sample port in the main waveguide. Leakage from this port into a cross guide provides an attenuated RF power sample. Applicant has found through investigation and experimentation that the typical directional coupler has significant sensitivity to reflected power that comes from the process chamber. The ratio of the reflected power effect on the forward power measurement is called directivity. Cross guide couplers are typically limited to directivity of -15 to -25 dB.

[0053] FIG. 9A shows the prior art configuration. RF power is delivered to the transmission line by an adaptor **81** (e.g. Maury Microwave Corp. C211D) and directed through the directional coupler **16** into a dummy load **82**. The dummy load absorbs all the power and there is no reflected power. FIG. 9C shows the same configuration with

power being delivered into a short **83**. The short reflects all the power. From the difference between the S21 frequency response graphs, FIGs. 9B and 9D, it is obvious that the measured forward power signal **20a** is corrupted by the reflected power signal.

[0054] Alternate designs of couplers can provide improved directivity, but at a prohibitive increase in size and cost. These make the alternate designs impractical for use in production microwave systems.

EXAMPLE

[0055] Applicants have discovered a novel solution that incorporates splitting the forward and reflected power measurement couplers and relocating the forward power coupler to the source side of the existing isolator. FIGs. 10A and 10C show the forward power coupler **51** and reflected power coupler **52** separated by isolator **53**. Isolator **53** shown in FIGs. 10A and 10C may be the same design as isolator **15** shown in FIG. 1. This unique solution provides high fidelity for the forward power signal and maintains all present capabilities of the power measurement design, with a small change in size and nominal increase in cost.

[0056] As shown in S21 measurement plots in FIGs. 10B and 10D the effect of reflected power between a dummy load **82** and a short **83** is mitigated. However, to ensure the accuracy of the forward power measurement relative to the process chamber in both amplitude and frequency, Applicants have further identified the need to account for the insertion loss of the isolator **53** in the calibration routine for the directional couplers.

[0057] Applicants have discovered that the crystal detector (e.g. Advanced Control Components p/n ACSP-2551) used to convert low level RF power to a DC control voltage has three significant problems when used in a high fidelity control system. The

first problem is a significant variation in output voltage as a function of temperature as shown in FIG. 4. The second problem is output roll-off as shown in FIG. 11 (Standard Detector Output) that eventually renders the detector useless for precision control at high power levels. The third problem is that crystal detectors generate their output voltage relative to local ground potential at the coupler and there is often a significant DC offset in ground potential at the measurement control circuit.

EXAMPLE

[0058] By ovenizing the crystal detectors **19'** and using a precision temperature controller to maintain the detector at a stable temperature above ambient, Applicants have found a cost effective, stable solution for the temperature sensitivity.

[0059] Applicants have further found that attenuating the RF signal from Coupler **51** to the crystal detector **19'** by the addition of a fixed attenuator **110** or equivalent improves the operating region resulting in greater DC output sensitivity (measured as VDC/watt).

[0060] Applicants have further provided ground isolation in the form of a DC to DC isolation amplifier **54** to ensure that a ground loop or DC level bias between the Crystal Detector and control system is eliminated. This ensures a high fidelity power signal.

[0061] Further improvement is obtained by amplifying the DC signal to ensure that it is in the upper/middle range (60% to 80%) of the Analog to Digital converter used by the RF control system **21**. Typical DC-DC amplifier gains of 5X are used to obtain 10 or more bits of resolution for each percent of HPA power at the upper end of the range. Without attenuation of the RF signal and subsequent amplification there may be less than 1 bit of digital resolution per percent of HPA power which is

inadequate for precision control. For legacy applications where field upgrades may be required to use existing calibration files, the Isolation Amplifier **54** may be equipped with a 1X amplification.

[0062] TWT Gain: Prior art in VFM control is designed to remove the non-linear frequency response of the traveling wave amplifier (see FIG. 2) and the transmission line. This is accomplished by a self calibration routine referred to as Autolevel.

[0063] The existing autolevel process involves the steps shown in FIG. 12. These include: **1201** Manually identifying saturation levels of the high power amplifier; **1202** Manually determining starting values for a power search routine; **1203** Selecting a power level; and, **1204** Starting an automated routine to generate an autolevel for a selected discrete power level. For each frequency in the swept band the routine adjusts the voltage controlled attenuator to obtain a measured output power level at the forward power coupler within +/- 10% of the selected discrete power level. The settings for the voltage controlled attenuator at that specific frequency are then stored in a table that is used in run-time operation. The next frequency is selected by the auto-level routine and the process is repeated until the full band is covered. **1205** Upon completion of the automated routine the operator must manually review the results and either accept (save the file) or repeat the process. **1206** the operator then selects another discrete power level and the routine is repeated. This is done until all power levels have been autoleveled. **1207** Upon completion of all power levels, the operator must then download the autolevel files to a control system.

[0064] The leveled powers generated by this process are normally sufficient for closed loop processes where a process control input (e.g., a temperature measurement) is used to call for more or less power to achieve a target temperature.

[0065] However this level of power accuracy is not sufficient for a repeatable precision process or a process where open loop process control is needed. An open-loop

process is typically defined as one where there are no automatic adjustments done by the control system.

[0066] As described in the following example a new technique for the autolevel process was invented to improve the fidelity of the power response versus frequency.

EXAMPLE

[0067] In this new autolevel process: **1301** the operator starts the fully automated autolevel routine; **1302** the autolevel routine automatically selects a starting frequency (currently it works from low to high, but this is not required) and **1303** adjusts the voltage controlled attenuator to a set point. **1304** The system records the power output at that setting. The voltage controlled attenuator is set to the next set point and the power level is recorded for that setting. **1305** This process is repeated until the routine detects saturation. Saturation is defined as the point at which an increase in input drive results in no increase (or a decrease) in output power from the high power amplifier. **1306** The routine stores the saturation power level in a diagnostic file. The autolevel routine automatically selects the next sample frequency and repeats the above process. The next frequency may be separated by a large measure from the first.

[0068] Applicants have discovered, surprisingly, that attenuator measurements at 65 discrete frequency intervals (64 sub-bands) can be sufficient to improve on the prior art which required power measurements and attenuator adjustments at each of the nominal 4096 frequencies used in the prior art calibration. The new technique has been demonstrated on a typical 800MHz to 1GHz swept frequency band. It will be appreciated that more discrete frequency levels may be desirable where multi-octave TWTs and passive components have greater variability across the broader

bandwidths of operation. The advantage of this invention is that the strategic sampling will be a more efficient calibration method.

[0069] 1307 Once the routine completes the necessary sampling of frequency scans, it will automatically generate an autolevel table. **1308** This table is then automatically downloaded to the control system. All of the above operations are automatic and do not require operator intervention.

[0070] The unique and novel capabilities of the new autolevel process are: 1. improved fidelity of power versus frequency as shown in FIGs. 14A and 14B; 2. Fully automatic operation; 3. Diagnostic file automatically generated for maintenance history; 4. Faster completion by strategic sampling of the frequency/power map rather than point by point completion; and 5. Compatibility with previous autolevel file formats

EXAMPLE

[0071] The novel methodology of generating the autolevel table by strategic sampling includes the use of a spline based surface fitting routine **1307** The surface fitting routine accepts a two-dimensional array of data representing the observed forward power as a function attenuation setting (row) and drive frequency (columns). The curve fitting routine fits C-splines to the input data and extracts autolevel files that have attenuation setting as a function of frequency at constant power.

[0072] In the present configuration, a C-spline curve fit is used to generate a 3-D autolevel data surface. Alternate curve fitting routines could also be used. It will be appreciated that in the present configuration the algorithm could be integrated or run separately as a subroutine.

[0073] System Controls: Automatic power regulation. Applicant has discovered there remain additional components within the microwave control system with thermal sensitivity that cannot be practically isolated in a controlled environment due to their size and power requirements. Furthermore some of these components such as the high power amplifier have a time-based drift that is not a function of the environment as shown in FIG. 15.

EXAMPLE

[0074] To ensure stable and repeatable power, Applicants have developed a novel control routine as shown in FIG. 16. This control routine provides automatic power regulation to provide corrected drive levels. Should the measured forward power signal **20a'** be high or low for any reason, the power regulator **161** output will be added to the current power command to generate an improved power setpoint.

[0075] The power control algorithm relies on the accuracy of the forward power measurement. This means that the isolated forward power measurement **51**, ovenized crystal detector **19'**, PAD offset, amplification/ground isolation **54** mentioned above are related to successful implementation of the algorithm.

[0076] The power control algorithm contains two important functions. The first is a limit on the rate of power adjustment to avoid too rapid a response. The second is a sensor "leash" that prevents adjustments beyond a preset amount. Alarms are set to notify the master control that the system is not able to maintain accurate power control.

We claim:

1. A broadband microwave heating apparatus comprising:

an applicator cavity for exposing a workpiece to microwave energy;
a microwave power supply connected to said cavity, said power supply comprising:

a small signal RF source comprising at least a voltage controlled microwave oscillator and a voltage controlled attenuator that are both thermally stabilized at a selected temperature above ambient;

a high power microwave amplifier to amplify said small signal to a usable power level for heating;

forward and reflected power detectors, said detectors separated from one another by a microwave isolator; and,

a control system using a power regulator to adjust output power using detected forward power compared to demanded forward power.

2. The apparatus of claim 1 wherein said small-signal RF source further includes a fixed attenuator and a bandpass filter.

3. The apparatus of claim 1 wherein all components of said small-signal RF source are mounted on a common thermal platform so that they are all maintained at a common temperature above ambient.

4. The apparatus of claim 1 wherein said forward and reflected power detectors are thermally stabilized at a selected temperature above ambient.

5. A broadband microwave power supply comprising:

a small signal RF source comprising at least a voltage controlled microwave oscillator and a voltage controlled attenuator that are both thermally stabilized at a selected temperature above ambient;

a high power microwave amplifier to amplify said small signal to a usable power level for heating;

forward and reflected power detectors, said detectors separated from one another by a microwave isolator; and,

a control system including a power regulator to adjust output power using detected forward power compared to demanded forward power.

6. The apparatus of claim 5 wherein said small-signal RF source further includes a fixed attenuator and a bandpass filter.

7. The apparatus of claim 5 wherein all components of said small-signal RF source are mounted on a common thermal platform so that they are all maintained at a common temperature above ambient.

8. The apparatus of claim 5 wherein said forward and reflected power detectors are thermally stabilized at a selected temperature above ambient

9. An integrated, low power microwave source comprising:

a voltage controlled oscillator (VCO);

a voltage controlled attenuator (VCA);

a heater and temperature control circuit; and,

a package containing said VCO, VCA, heater, and temperature control circuit and having external connections for DC power, DC frequency control voltage, DC amplitude control voltage, and RF signal out.

10. The microwave source of claim 9 wherein said package comprises a printed circuit board.

11. The microwave source of claim 9 wherein said package comprises a hybrid circuit module.

12. A method of heating materials using broadband microwave power, comprising the steps of:

- placing a selected workpiece in a multi-mode microwave applicator cavity;

- providing a microwave power supply in communication with said cavity, said power supply including a small-signal RF generating circuit, a high power microwave amplifier, and forward and reflected power detectors, said detectors separated from one another by an isolator;

- heating at least some of the components of said small-signal RF circuit to a selected temperature above ambient;

- providing a control system to perform the following functions:

 - run an autoleveling routine to automatically generate an autolevel table and download said autolevel table to said control system;

 - provide an automatic power control system to limit the rate of power adjustment; and,

 - applying microwave power into said applicator cavity under the control of said control system to heat said workpiece.

13. The method of claim 12 wherein said autoleveling routine includes a spline-based surface fitting routine.

14. The method of claim 12 further including the step of heating said forward and reflected power detectors to a selected temperature above ambient.

15. The method of claim 12 wherein said automatic power control system includes an alarm function to notify the master control if the system is not able to maintain accurate power control.